

Amendment to the Specification

Please amend the Paragraph beginning on page 6, line 5 of the Application as originally filed to state the following:

During the process of encapsulating a MEMS or a micromachined device, certain underlying conditions for the process as a whole are typically preset. Conditions, such as the atmospheric composition of the processing environment, can have a substantial impact on process and can affect the resulting product. For the process of the creation of a micro-encapsulated package to protect the MEMS or micromachined device, typically an inert gas atmosphere, including but not limited to an atmosphere comprised in whole or in part of argon, nitrogen, helium, neon, sulfur hexafluoride, or air, with a pressure above 1 Pascal is utilized. Also, during the entire process the temperature of the atmosphere or the devices should typically not rise above 600° C or above a temperature sufficient to melt or damage a MEMS or micromachined device.